TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (Ultra-High-Speed U-MOSIII)

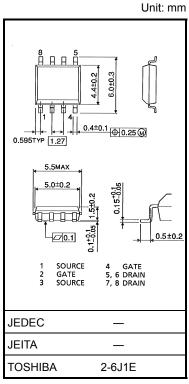
# **TPC8213-H**

High-Efficiency DC / DC Converter Applications Notebook PC Applications Portable-Equipment Applications

- Small footprint due to small and thin package
- · High-speed switching
- Small gate charge: Q<sub>SW</sub> = 2.9 nC (typ.)
- Low drain-source ON-resistance:  $R_{DS (ON)} = 40 \text{ m}\Omega$  (typ.)
- High forward transfer admittance: |Y<sub>fs</sub>| =11 S (typ.)
- Low leakage current: I<sub>DSS</sub> = 10 μA (max) (V<sub>DS</sub> = 60 V)
- Enhancement mode:  $V_{th} = 1.1$  to 2.3 V ( $V_{DS} = 10$  V,  $I_D = 1$  mA)

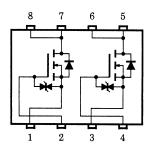
### **Absolute Maximum Ratings (Ta = 25°C)**

Cha	racteristic	Symbol	Rating	Unit	
Drain-source vo	Itage	$V_{DSS}$	60	V	
Drain-gate volta	ge (R <sub>GS</sub> = 20 kΩ)	$V_{DGR}$	60	V	
Gate-source vol	tage	V <sub>GSS</sub>	±20	V	
Drain current	D C (Note 1)	I <sub>D</sub>	5	Α	
Diam current	Pulse (Note 1)	I <sub>DP</sub>	60 60 ±20 5 20 1.5 1.1 0.75 0.45 90 5 0.087 150	A	
Drain power	Single-device operation (Note 3a)	P <sub>D (1)</sub>	1.5	W	
dissipation (t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D (2)</sub>	1.1		
Drain power dissipation (t = 10 s) (Note 2b)	Single-device operation (Note 3a)	P <sub>D (1)</sub>	0.75	W	
	Single-device value at dual operation (Note 3b)	P <sub>D 2)</sub>	0.45		
Single-pulse ava	lanche energy (Note 4)	E <sub>AS</sub>	90	mJ	
Avalanche curre	nt	I <sub>AR</sub>	5	Α	
Repetitive avalar (Note	nche energy e 2a, Note 3b, Note 5)	E <sub>AR</sub>	0.087	mJ	
Channel tempera	ature	T <sub>ch</sub>	150	°C	
Storage tempera	ture range	T <sub>stg</sub>	-55~150	°C	



Weight: 0.085 g (typ.)

# **Circuit Configuration**



Note: For Notes 1 to 5, refer to the next page.

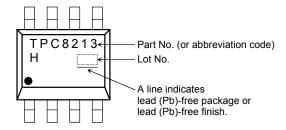
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

#### Thermal Characteristics

Characteristic	Symbol	Max	Unit		
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3		
(t = 10 s) (Note 2a)	Single-device value at dual operation (Note 3b)	R <sub>th (ch-a) (2)</sub>	114	°C/W	
Thermal resistance, channel to ambient	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	167	C/VV	
(t = 10 s) (Note 2b)	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	278		

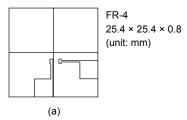
# Marking

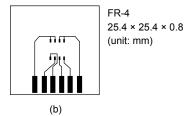


Note 1: The channel temperature should not exceed 150°C during use.

#### Note 2:

- a) Device mounted on a glass-epoxy board (a)
- b) Device mounted on a glass-epoxy board (b)





#### Note 3:

- a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is only applied to one device.)
- b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.)

Note 4:  $V_{DD}$  = 24 V,  $T_{ch}$  = 25°C (Initial), L = 5 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 5.0 A

Note 5: Repetitive rating: pulse width limited by maximum channel temperature

Note 6: • on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)

Week of manufacture
(01 for first week of year, continuing up to 52 or 53)

Year of manufacture
(The last digit of the calendar year)

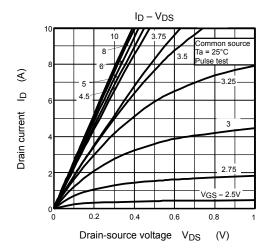
# **Electrical Characteristics (Ta = 25°C)**

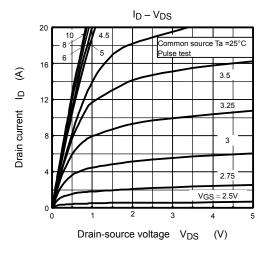
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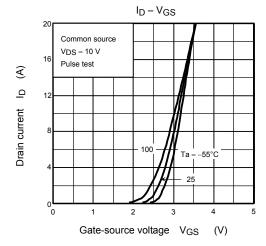
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cutoff curr	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	10	μΑ
Drain-course br	Danier and the saled area and the saled		I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
Dialii-source bi	eakdown voltage	V <sub>(BR) DSX</sub>			_		
Gate threshold v	/oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.1	_	2.3	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 2.5 A		45	56	mΩ
Dialii Source O	IV-I esistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V , I <sub>D</sub> = 2.5 A	—     40     50       5.5     11     —		50	11122
Forward transfe	r admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V , I <sub>D</sub> = 2.5 A	) = 2.5 A 5.5 11 -		_	S
Input capacitano	ce	C <sub>iss</sub>		_	625	_	pF
Reverse transfe	r capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	35	_	
Output capacitance		C <sub>oss</sub>		_	175	_	
Switching time  Total gate charge (gate-source plus (Note 7)  Gate-source charge (source charge)	Rise time	t <sub>r</sub>	V <sub>GS</sub> 10 V	_	4	_	
	Turn-on time	t <sub>on</sub>		ı	10	_	nc
	Fall time	t <sub>f</sub>		_	2	_	ns
	Turn-off time	t <sub>off</sub>		_	19	_	
Total gate charge (gate-source plus gate-drain) (Note 7)		0	$V_{DD} \simeq 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		11	_	
		$Q_g$	$V_{DD} \simeq 48 \; V, \; V_{GS} = 5 \; V, \; I_D = 5 \; A$	_	6	_	
Gate-source charge 1		Q <sub>gs1</sub>		_	1.6	_	nC
Gate-drain ("Miller") charge		Q <sub>gd</sub>	$V_{DD} \simeq 48 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	2.4	_	
Gate switch cha	rge	Q <sub>SW</sub>	]	_	2.9	_	

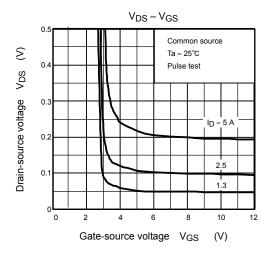
# Source-Drain Ratings and Characteristics (Ta = 25°C)

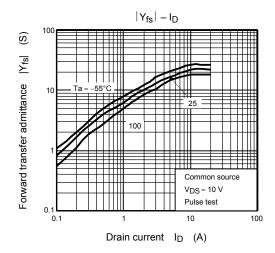
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	20	Α
Forward voltage (diode)		$V_{DSF}$	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V		_	-1.2	V

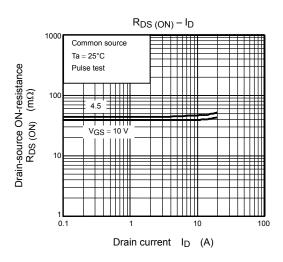


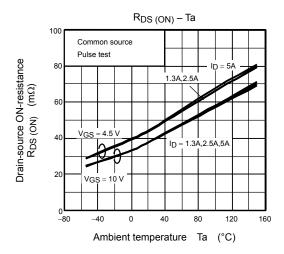


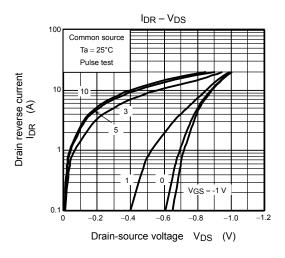


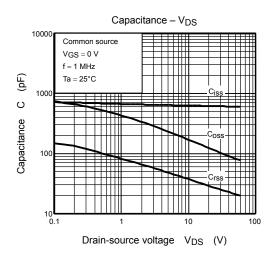


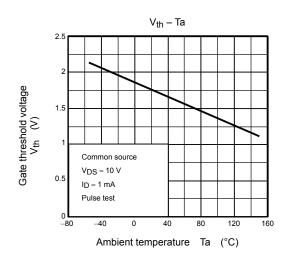


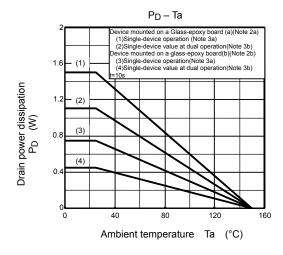


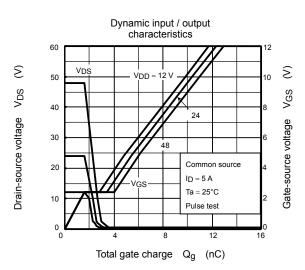


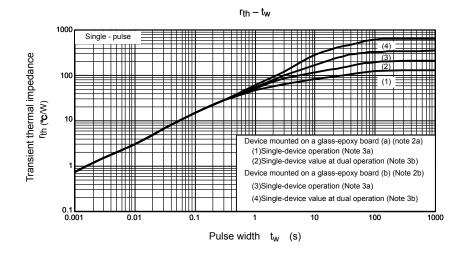


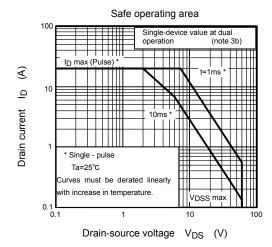












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